Art 19

EXPLANATION UNDER ARTICLE 19 (1) OF TREATY

In the correction of claims 1 and 2, it has been specified that the formation of network circuits on both faces of insulating substrate is one of the composing elements of the invention.

In the example of prior art, network circuits are formed only on the surface of insulating substrate.

The present invention has the construction that network circuits are formed on both faces of insulating substrate, which improves utility of surface on insulating substrate. Use of both faces of insulating substrate for network circuits enables enlargement in circuit size to improve stability in performance of circuit elements. For example, variation in resistance value can be controlled on resistor element. It is able to make production procedure easy. These are the effects of the invention.

In the correction of claim 3, the construction of network circuits shown in FIGs. 1 and 2 has been clarified. The correction has specified the difference of construction between the network circuit of prior art and ones of the invention shown in FIGs. 1 and 2. Each of the network circuits shown in the figures has two of the elements (a) to (d) described in claim 3.

In the correction of claim 4, it has been specified that a chip network component of the invention can be mounted turned 180 degrees along the surface of the component.

In the correction of claims 5 and 6, the means of discriminating face of the component has been specified.

Replaced by corrected copy (Art. 19 amendment)

WHAT IS CLAIMED

1. A surface mounting chip network component having an even number of network circuits formed on the surface of insulating substrate, each of the network circuits having three or more odd number of terminals, comprising an equal number of said terminals to be arranged each of the facing sides on said insulating substrate.

2. A surface mounting chip network component having an even number of network circuits formed on the surface of insulating substrate, each of the network circuits having three or more odd number of terminals, comprising said terminals to be arranged on each of the sides point-symmetrically with respect to the center of the surface of said substrate.

3. A surface mounting chip network component according to claim 1 or 2, wherein all terminals of the network circuits are arranged to locate on either of a pair of facing sides on the insulating substrate, and major terminals of a network circuit are located on the opposite side to the side where neighboring circuit has major terminals.

4. A surface mounting chip network component according to claim 3, wherein one, two, four, eight or sixteen pairs of equivalent network circuits are included and all terminals are corresponding to individual network circuit arranged point-symmetrically with respect to the center of the surface of the insulating substrate.

5. A surface mounting chip network component according to claim 1, 2, 3 or 4, wherein one or more network circuits with circuit elements are formed on both faces of the insulating substrate.

6. A surface mounting chip network component according to claim 1, 2, 3, 4 or 5, wherein network circuit is voltage divider.